



# SOT1226

plastic, leadless thermal enhanced extremely thin small outline package; no leads; 5 terminals; 0.48 mm pitch; 0.8 mm x 0.8 mm x 0.35 mm body

30 May 2022

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	X2SON5
<b>Package type industry code</b>	X2SON5
<b>Package style descriptive code</b>	HXSON (thermal enhanced extremely thin small outline; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Number of package outline detail graphic references</b>	0
<b>Issue date</b>	18-4-2012
<b>Manufacturer package code</b>	SOT1226
<b>Footprint dimensions (mm)</b>	1.2 x 1
<b>Footprint area (mm<sup>2</sup>)</b>	1.2

Table 1. Package summary

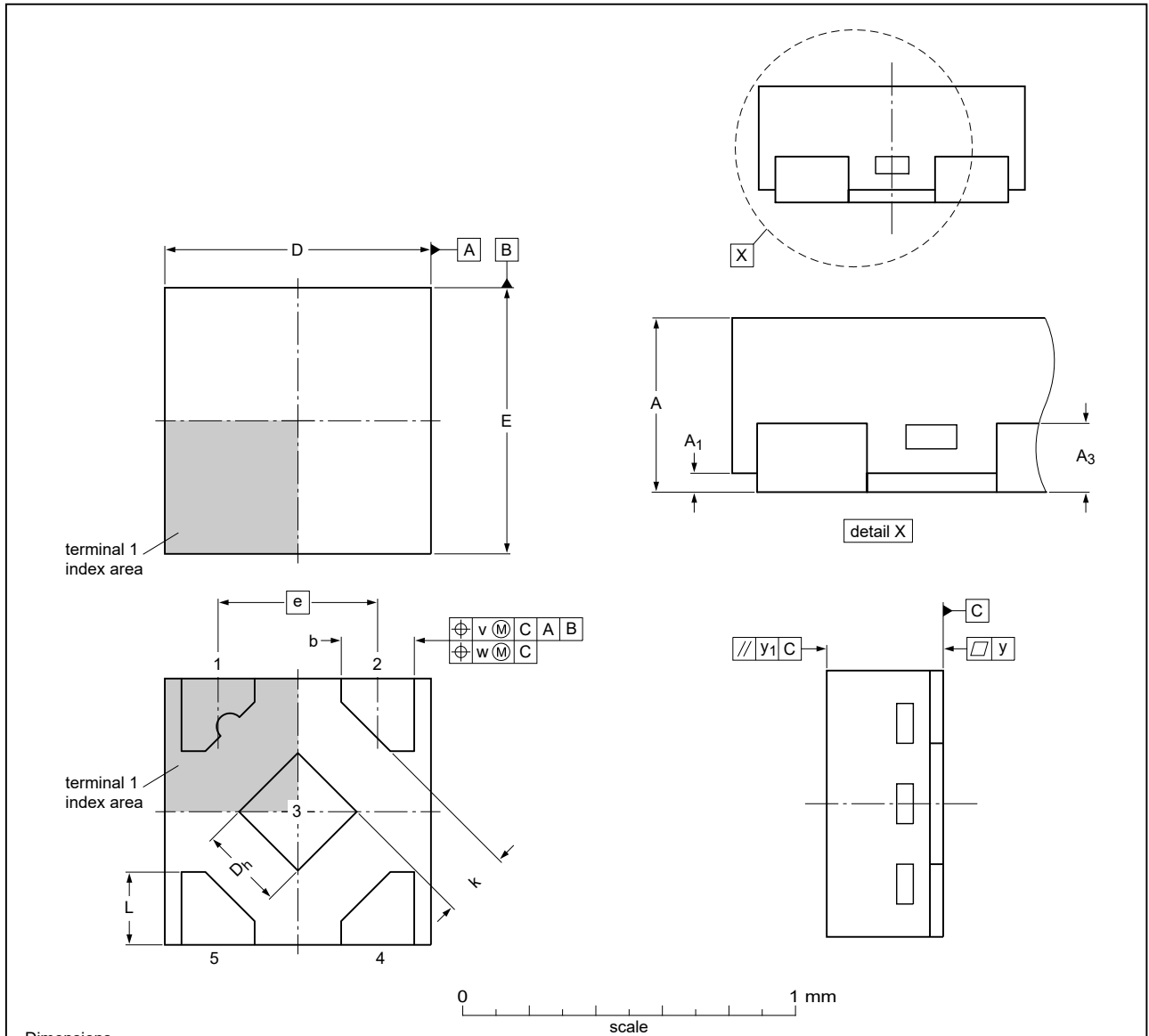
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.75	-	0.8	0.85	mm
E	package width	0.75	-	0.8	0.85	mm
A	seated height	-	-	-	0.35	mm
e	nominal pitch	-	-	0.48	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	5	-	

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## 2. Package outline

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226



Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	A <sub>3</sub>	D	D <sub>h</sub>	E	b	e	k	L	v	w	y	y <sub>1</sub>
max	0.35	0.04	0.128	0.85	0.30	0.85	0.27			0.27				
mm	nom			0.80	0.25	0.80	0.22	0.48		0.22	0.1	0.05	0.05	0.05
min			0.040	0.75	0.20	0.75	0.17		0.20	0.17				

Note

1. Dimension A is including plating thickness.
2. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References				European projection	Issue date
	IEC	JEDEC	EIAJ			
SOT1226						<del>12-04-10</del> 12-04-25

Fig. 1. Package outline X2SON5 (SOT1226)

plastic, leadless thermal enhanced extremely thin small outline package; no leads; 5 terminals; 0.48 mm pitch; 0.8 mm x 0.8 mm x 0.35 mm body

### 3. Soldering

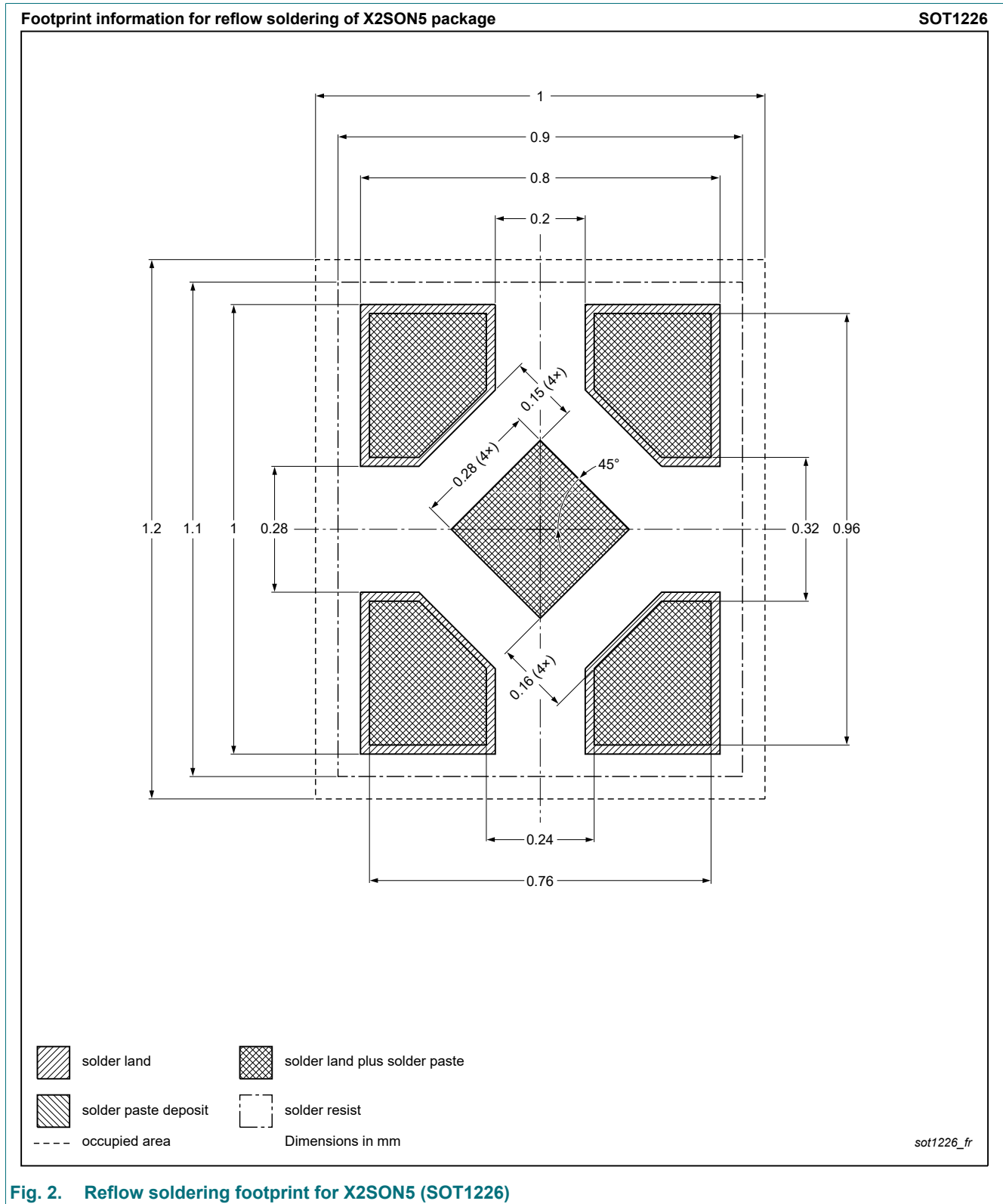


Fig. 2. Reflow soldering footprint for X2SON5 (SOT1226)

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For sales office addresses, please send an email to: [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)  
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